Docket No.: 135371 (1306-40)



licants:

Slawomir RUBINSZTAJN, et al.

Serial No:

10/654,378

Filed:

September 3, 2003

For:

SOLVENT-MODIFIED RESIN SYSTEM

CONTAINING FILLER THAT HAS HIGH

Tg, TRANSPARENCY AND GOOD RELIABILITY IN WAFER LEVEL UNDERFILL APPLICATIONS

Dated: November 25, 2003

Commissioner for Patents P.O. Box 1450 Alexandria, New York 22313-1450

## **CHANGE OF ATTORNEY'S ADDRESS IN APPLICATION**

Please send all corresponce and direct all telephone calls for this application as follows:

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Respectfully submitted,

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## **CERTIFICATE OF MAILING UNDER 37 C.F.R. §1.8(a)**

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail, postpaid in an envelope, addressed to the: Commissioner for Patents, P.O. Box 1450, Alexandria, New York 22313-1450 on November 25, 2003.

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